

IKA professional distribution board, IP65 + clamps

Powering Business Worldwide*

Part no. IKA-1/8-ST Catalog No. 174196 Eaton Catalog No. IKA-1/8-ST

Del	liver	nro	gram
		, p. c	grain

Basic function			Basic device
Product function			Installation distribution boards
Product range			IKA professional DBO
Design			Surface mounted
Installation site			Indoor
Type of installation			Surface mounting
Door/Flap			Transparent
Degree of Protection			IP65
Colour			Grey
Module rack			Single-rail
Shroud for protection against accidental contact			Plastic
Rows	Count		1
Module units per row			8
Description			IP65 Protection Class II Plastic enclosure gray (RAL 7035)
Cable entries			Metric cable entries on top and bottom, back plate
PE and N terminals design			Screw terminals
PE and N terminals	Number x cross- sectional area	mm ²	PE: 4 x (2.5 - 6) + 4 x (4 - 10) + 1 x (16 - 35) N: 4 x (2.5 - 6) + 4 x (4 - 10) + 1 x (16 - 35)
Equipment supplied			Basic device Device support rails Neutral-/protective conductor terminal Locking screws can be sealed Sealing caps Current circuit designation

Technical data

General

Standards			EN 62208, IEC/EN 60670-24
RoHS (in accordance with Directive 2002/95/EC of the European Parliament and Council)			conform
Ambient temperature		°C	-25 - +40
Degree of Protection			IP65
Protection class			II (totally insulated)
Rated operational voltage	Ue	V AC	415
Rated frequency	f	Hz	50
Material characteristics			
Material			ABS (plastic)
Colour			Gray (RAL 7035)
Material properties			
Mechanical			
Impact resistance			IK08

Design verification as per IEC/EN 61439

Technical data for design verification			
Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P_{V}	CO	14
Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P_V	CO	29

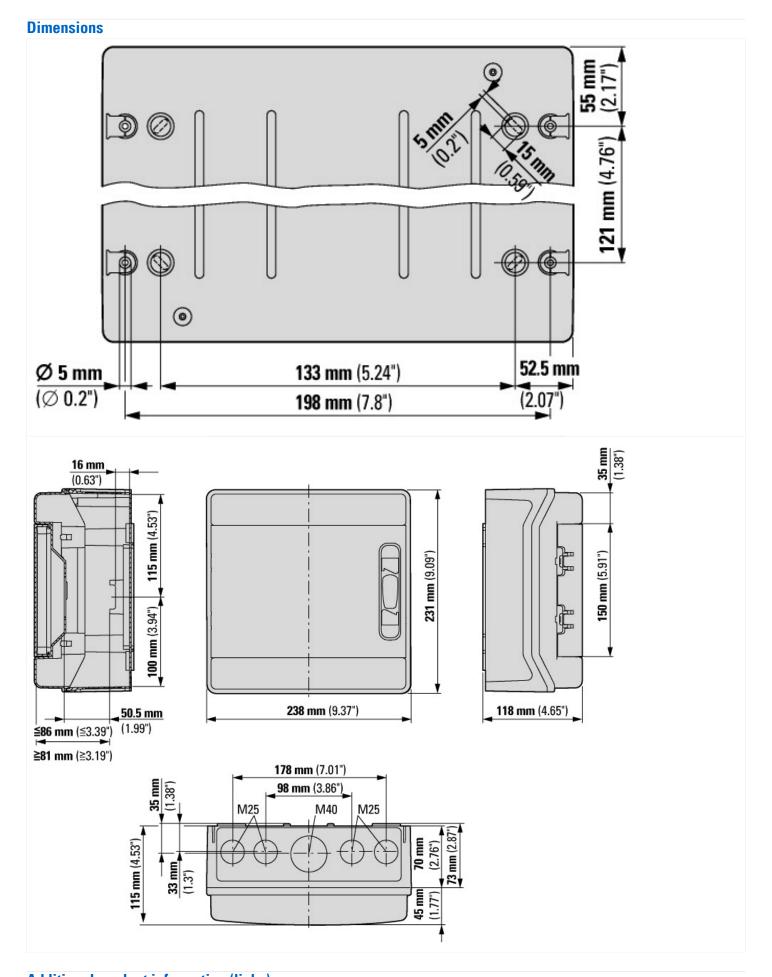
10.2.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat and fire due internal electric effects 10.2.4.3 Sterification of resistance of insulating materials to abnormal heat and fire due internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.2.7 Inscriptions 10.2.7 Inscriptions 10.2.8 Mechanical impact 10.3.1 Verification of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Incorporation of switching devices and components 10.5 Incorporation of switching devices and components 10.6 Incorporation of switching devices and components 10.9 Insulation properties 10.9 Insulation properties 10.9.2 Power-frequency electric strongth 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.13 Mechanical function 10.13 Mechanical function 10.13 Mechanical function 10.13 Mechanical function 10.14 Meets the product standard's requirements. Meets the product standard's requirements. Meets the panel builder's responsibility. In the panel builder's responsibility.	EC/EN 61439 design verification	
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	10.13 Mechanical function	Meets the product standard's requirements.

Technical data ETIM 6.0

Distribution boards (EG000023) / Small distribution board (EC000214)

Electric engineering, automation, process control engineering / Electrical installation, device / Electrical distribution system (incl. small distribution board) / Small distribution board (ecl@ss8.1-27-14-24-09 [ACN387008])

(**************************************		
Mounting method		Surface mounting
Number of rows		1
Width in number of modular spacings		8
Type of cover		Door
Cover model		With notch
Transparent cover/door		Yes
Material housing		Plastic
Height	mm	231
Width	mm	238
Depth	mm	115
Built-in depth	mm	70
Internal depth	mm	60
DIN-rail		Yes
With mounting plate		No
Extension possible		Yes
EMC-version		No
Colour		Grey
RAL-number		7035
Degree of protection (IP)		IP65
With lock		No



Additional product information (links)

IL014003Z IKA compact distribution board	
IL014003Z IKA compact distribution board	ftp://ftp.moeller.net/DOCUMENTATION/AWA_INSTRUCTIONS/IL014003ZU2015_03.pdf
Product overview (Web)	http://www.eaton.eu/DE/Europe/Electrical/ProductsServices/Residential/index.htm